

Alliance Group Technologies Company Kokomo, Inc.

Electronics Division

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Contract Electronic Manufacturing

Contract Electronic Manufacturing of Bare Printed Circuit Boards, Printed Circuit Board Assemblies and Electro-Mechanical box builds using state of the art facilities to insure your programs ultimate success

- **Lead-Free/RoHS compliant processing available**
- Automated SMT assembly - using MYDATA Equipment
- Double-Sided Reflow
- Circuit board layout and design
- Bare Printed Circuit Boards with blind and buried vias
- Maximum placement rate: up to 12,000 chips per hour
- Minimum Chip Size: 0402
- Maximum IC pin pitch: .015 inch
- Ball grid arrays, chip scale packages, fine pitch placement and rework
- Kitting and inventory stocking programs
- Engineering, purchasing, project management, quality control and inventory management resources manage your programs daily requirements

Quality Assurance Program

- ISO9001:2000 Registered
- Incoming Component inspection and verification
- ESD Compliant Facility (ANSI/ESD S20.20-1999)
- Equipment and measurement tool(s) calibration program
- Final packaging specifications focus on quality assurance of product until delivery to customers

Assembly Processes

- Solder paste screen printer
- Automated fluid dispensing robot
- Surface mount placement automation – MYDATA Equipment
 - Vision system for placement of fine pitch and BGA components
 - .015 inch minimum device pin pitch
 - Capable of placing chips as small as 0402
- Through-hole placement of leaded components
- Reflow, no clean and water soluble processes
 - One five-zone and one seven-zone reflow oven
 - Lead-free or lead-based solder paste
 - Four zone wave solder with multiple wave profiles
 - M.O.L.E. oven profiling equipment
- BGA placement, BGA rework and X-ray inspection
 - BGA, Micro BGA, QFP and micro chip scale package placement and rework
 - Sniper BGA rework station with onboard software for reflow thermal profiling
 - X-ray equipment for fine pitch component, BGA, and bareboard inspection
- Final Product Testing
 - Functional Testing
 - Flash programming
 - EPROM/PROM programming
- Workcell manufacturing for final assembly and box build products
 - Kanban inventory management
 - Assembly automation and process streamlining for small to medium volume electromechanical builds